Ebara F-REX 300
Chemical Mechanical Polishing System

- **Currently Configured for 300mm wafer sizes**
- **MFG Date: 2004**
- **Factory Interface (FI):**
  - **Frame Config: Metro Ready**
  - **Load-port Type: (3) Asyst ISO**
- **Polisher (L/R):**
  - **Polishing Heads: 300mm AL Head, Gen. II**
  - **Endpoint: TCM & Friction**
  - **Platen Type (Speed): Ceramic (SIC), 10-150 RPM**
  - **Platen Pad Conditioner: Scan Dresser 4” Disc, Sweep Driven**
  - **Slurry Delivery: CLC Delivery**
  - **Slurry Line1: ASAHI 25-250ml/min (low flow rate)**
  - **Slurry Line 2: none**
  - **Slurry Line 3: none**
  - **Wafer Slip-out Sensor: n/a**
  - **Platen Cooling Flow Monitor: Tokyo KEISO**
  - **Platen Cooling Temp Monitor: User Configurable alarm Settings**
  - **Dresser DIW Flow Meter: Flow Range 1.0-1.5 L/min**
  - **Atomizer: Yes**
- **Cleaner:**
  - **Cleaner 1 Type: Roller Brush**
    - **Chem. Delivery Type: (1) Chem CLC 0.0-1.0 L/min (alarm capability)**
    - **Chemical 1 Upper Flow Meter: 0.0-1.0 L/min**
    - **Chemical 1 Lower Flow Meter: 0.0-1.0 L/min**
    - **Bevel Edge Cleaning: n/a**
  - **Spin Rinse Drier: Pencil Brush**
    - **Chem. Delivery Type: (1) Chem CLC 0.0-1.0 L/min (alarm capability)**
- **Options:**
  - **Robot D: Yaskawa**
  - **Robot R: Yaskawa**
  - **Robot L: Yaskawa**
  - **Status Lamp (RYGB, Front/Rear)**
  - **Monitor 1: Front**
  - **Monitor 2: L-Side**
  - **Monitor 3: R-Side**
  - **EPD Monitor: R-Side**

- **Software:**
  - **Main SW ver: 7.5.02**
  - **CPU-1 (OS/9) ver: 7.5.02**
  - **CPU-2 (OS/9) ver: 7.5.00**
  - **Touch Panel Control ver: 7.5.00**
  - **Touch Panel Drawing ver: 7.5.00**
  - **Online ver: 7.5.00**
  - **ME10/ME20 ver: 2.4.30.5**
- **Communication:**
  - **Controller (Logic): VME**
  - **Controller (Process Database): Touch Panel**
- **Facility:**
  - **Seismic Support: Bracket locations to be provided**
  - **Chemical Connections: Bottom**
  - **Exhaust Connections: Top**
  - **Gas Connections: Bottom**
  - **Drain Connections: Bottom**